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DECLARATION FOR UNITED STATES PATENT APPLICATION,
POWER OF ATTORNEY, DESIGNATION OF CORRESPONDENCE ADDRESS

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and that I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

HIGH-DENSITY MULTI-LAYER MICROCOIL AND METHOD FOR FABRICATING THE SAME
the specification of which

[X] is attached hereto.

[] was filed on _____, as Application Serial No.

and was amended on _____ [if applicable].

[] was filed under the Patent Cooperation Treaty on _____

Serial No. _____, the United States of America being designated.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose to the Patent and Trademark Office information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)	Priority Claimed			
Number	Country	Date Filed	Yes	No

91109741 Taiwan, R.O.C. May 10, 2002 Yes

I hereby appoint the following attorneys to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith: Steven M. Rabin (Reg. No. 29,102), Thomas M. Champagne (Reg. No. 36,478), Robert H. Berdo, Jr. (Reg. No. 38,075), and David S. Lee (Reg. No. 38,222), 1101 14 Street, N.W., Suite 500, Washington, D.C. 20005, Telephone: (202) 659-1915; Fax: (202) 659-1898. Address all correspondence to RABIN & CHAMPAGNE, P.C., 1101 14 Street, N.W., Suite 500, Washington, D.C. 20005.

The undersigned hereby authorizes the U.S. attorneys named herein to accept and follow instructions from the undersigned's assignee, if any, and/or, if the undersigned is not a resident of the United States, the undersigned's domestic attorney, patent attorney, patent agent, or patent representative as to any action to be taken in the Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and the undersigned. In the event of a change in the person(s) from whom instructions may be taken, the U.S. attorneys named herein will be so notified by the undersigned.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Signature: Morris P.F. Liang Date: July 8, 2002
First Joint Inventor: Morris P.F. LIANG
Citizenship: Taiwan, R.O.C.
Residence and Post Office Address:
3F-2, No. 70, Min-Te Rd., Chu-Tung, Hsinchu Hsien, Taiwan, R. O. C.

Signature: Sway Chuang Date: July 8, 2002
Second Joint Inventor: Sway CHUANG
Citizenship: Taiwan, R.O.C.
Residence and Post Office Address:
1F, Bldg. 52, No. 195, Sec. 4, Chung-Hsing Rd., Chu-Tung, Hsinchu Hsien, Taiwan, R. O. C.

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Page 2 of 2

Signature:

Frank K. C. Fan

Date: July 8, 2002

Third Joint Inventor: Frank K.C. FAN

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address:

3F, No. 1, Lane 43, Pei-Yin St., Hsinchu City, Hsinchu, Taiwan, R. O. C.

Signature:

Chen Chung Kao

Date: July 8, 2002

Fourth Joint Inventor: Chen Chung KAO

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address:

1F, Bldg. 52, No. 195, Sec. 4, Chung-Hsing Rd., Chu-Tung, Hsinchu Hsien, Taiwan, R. O. C.

Signature:

Date: _____, 2002

Fifth Joint Inventor:

Citizenship:

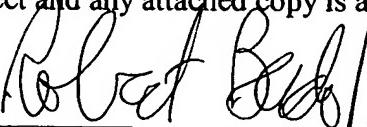
Residence and Post Office Address:

RECORDATION COVER SHEET - PATENT APPLICATION

COPY

NAME OF CONVEYING PARTY	:	Morris P.F. LIANG, Sway CHUANG, Frank K.C. FAN and Chen Chung KAO
NAME OF RECEIVING PARTY	:	INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE
ADDRESS OF RECEIVING PARTY	:	No. 195, Chung-Hsing Rd., Sec. 4, Chu-Tung, Hsinchu Hsien, Taiwan, R.O.C.
NATURE OF CONVEYANCE	:	Assignment of U.S. Patent Application
CONVEYANCE EXECUTION DATE	:	July 8, 2002
PATENT APPLICATION NO.	:	To be assigned
PATENT APPLICATION FILING DATE	:	July 23, 2002
APPLICATION FILED TOGETHER WITH THIS DOCUMENT	:	YES
APPLICATION EXECUTION DATE	:	July 8, 2002
CORRESPONDENCE ADDRESS	:	RABIN & BERDO, P.C. 1101 14th Street, N.W., Suite 500 Washington, DC 20005 (Customer No: 23995)
ATTORNEY REFERENCE	:	TAIW 125
TOTAL NUMBER OF PATENTS AND APPLICATIONS INVOLVED	:	One
TOTAL FEE PAID	:	\$40.00
METHOD OF PAYMENT	:	<input checked="" type="checkbox"/> Enclosed <input type="checkbox"/> Authorized to be charged to deposit account

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.


Robert H. Berdo, Jr. (Reg. No. 38,075)

July 23, 2002
Date

Total number of pages including cover sheet, attachments and document: 2.

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ASSIGNMENT OF APPLICATION FOR UNITED STATES LETTERS PATENT

WHEREAS, Morris P.F. LIANG, Sway CHUANG, Frank K.C. FAN, Chen Chung KAO hereinafter referred to collectively as the assignor, has invented a certain improvement relating to HIGH DENSITY MULTI-LAYER MICROCOIL AND METHOD FOR FABRICATING THE SAME, [X] the inventor(s) declaration for said application being executed concurrently with the execution of this instrument; said application to be filed in the United States Patent and Trademark Office; [] said application having been filed in the United States Patent and Trademark Office on _____, authorization being hereby given to my attorneys, Steven M. Rabin, Thomas M. Champagne, Robert H. Berdo, Jr., and David S. Lee, of RABIN & CHAMPAGNE, P.C., 1101 14th Street, N.W., Suite 500, Washington, D.C. 20005, to insert here in parentheses (Application Serial No. _____) the application serial number of said application when known; [] said application having been filed under the Patent Cooperation Treaty on _____, Serial No.) _____, the United States of America being designated.

AND WHEREAS Industrial Technology Research Institute who's address is No. 195, Sec. 4, Chung-Hsing Rd., Chu-Tung, Hsinchu Hsien, Taiwan, R. O. C., hereinafter referred to as the assignee, is desirous of acquiring the entire right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof;

NOW THIS WITNESSETH, that for and in consideration of One Dollar (\$1.00), and other good and valuable consideration paid by said assignee to said assignor, the receipt of which is hereby acknowledged, said assignor hereby assigns, sells and transfers to said assignee, and said assignee's successors and assigns, the full and exclusive right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof; said assignee, and said assignee's successors and assigns, to have, hold, exercise and enjoy the said application, including any and all divisions and continuations thereof, and the said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges and advantages in anywise arising from or appertaining thereto, for and during the term or terms of any and all such patents when granted, including any and all renewals, reissues and prolongations thereof, for the use and benefit of said assignee, and said assignee's successors and assigns, in as ample and beneficial a manner as the said assignor might or could have held and enjoyed the same, if this assignment had not been made.

AND said assignor hereby agrees to perform, upon the request of said assignee, or said assignee's successors or assigns, any and all acts relating to the obtaining or to the asserting of said patents, including any and all renewals, reissues and prolongations thereof.

AND said assignor authorizes and requests the Commissioner of Patents and Trademarks to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said assignee, and said assignee's successors and assigns, in accordance herewith.

Morris P.F. LIANG
Name of sole or first inventor

Morris P.F. Liang
Signature

July 8, 2002

Sway CHUANG
Name of second inventor, if any

Sway Chuang
Signature

July 8, 2002

Frank K.C. FAN
Name of third inventor, if any

Frank K.C. Fan
Signature

July 8, 2002

Chen Chung KAO
Name of fourth inventor, if any

Chen Chung Kao
Signature

July 8, 2002

Name of fifth inventor, if any

Signature

Date